



**THE DATASHEET OF  
LMH0036SQ/NOPB**



## LMH0036 SD SDI Reclocker with 4:1 Input Multiplexer

Check for Samples: [LMH0036](#)

### FEATURES

- Supports SMPTE 259M (C) Serial Digital Video Standard
- Supports 270 Mbps Serial Data Rate Operation
- Supports DVB-ASI at 270 Mbps
- Single 3.3V Supply Operation
- 360 mW Typical Power Consumption
- Integrated 4:1 Multiplexed Input
- Two Differential, Reclocked Outputs
- Choice of Second Reclocked Output or Low-Jitter, Differential, Data-Rate Clock Output
- Single 27 MHz External Crystal or Reference Clock Input
- Lock Detect Indicator Output
- Output Mute Function for Data and Clock
- Auto/Manual Reclocker Bypass
- Differential LVPECL Compatible Serial Data Inputs and Outputs
- LVCMOS Control Inputs and Indicator Outputs
- 48-Pin WQFN Package
- Industrial Temperature Range: -40°C to +85°C
- Footprint Compatible with the LMH0056 and LMH0356

### APPLICATIONS

- SDTV Serial Digital Video Interfaces for:
  - Digital Video Routers and Switchers
  - Digital Video Processing and Editing Equipment
  - DVB-ASI Equipment
  - Video Standards and Format Converters

### DESCRIPTION

The LMH0036 SD SDI Reclocker with 4:1 Input Multiplexer retimes serial digital video data conforming to the SMPTE 259M (C) standard. The LMH0036 operates at the serial data rate of 270 Mbps, and also supports DVB-ASI operation at 270 Mbps. The LMH0036 includes an integrated 4:1 input multiplexer for selecting one of four input data streams for retiming.

The LMH0036 retimes the incoming data to suppress accumulated jitter. The LMH0036 recovers the serial data-rate clock and optionally provides it as an output. The LMH0036 has two differential serial data outputs; the second output may be selected as a low-jitter, data-rate clock output. Controls and indicators are: serial clock or second serial data output select, manual rate select input, SD indicator output, lock detect output, auto/manual data bypass, and output mute. The serial data inputs, outputs, and serial data-rate clock outputs are differential LVPECL compatible. The CML serial data and serial data-rate clock outputs are suitable for driving 100Ω differentially terminated networks. The control logic inputs and outputs are LVCMOS compatible.

The LMH0036 is powered from a single 3.3V supply. Power dissipation is typically 360 mW. The device is housed in a 48-pin WQFN package.



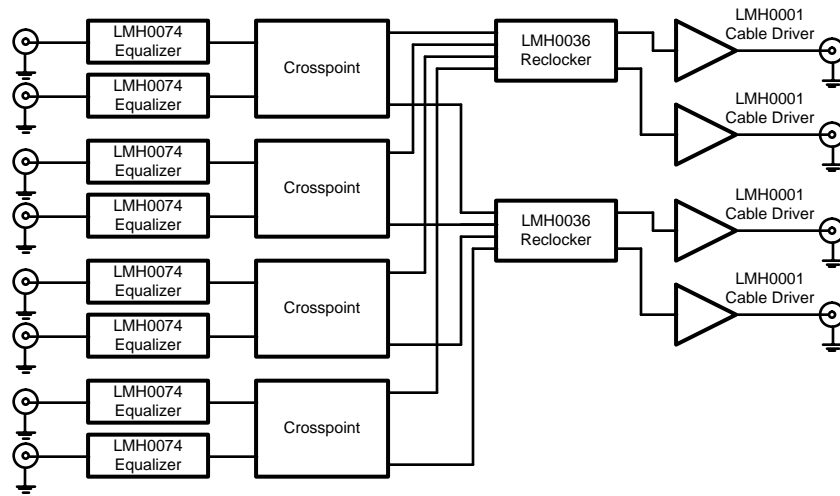
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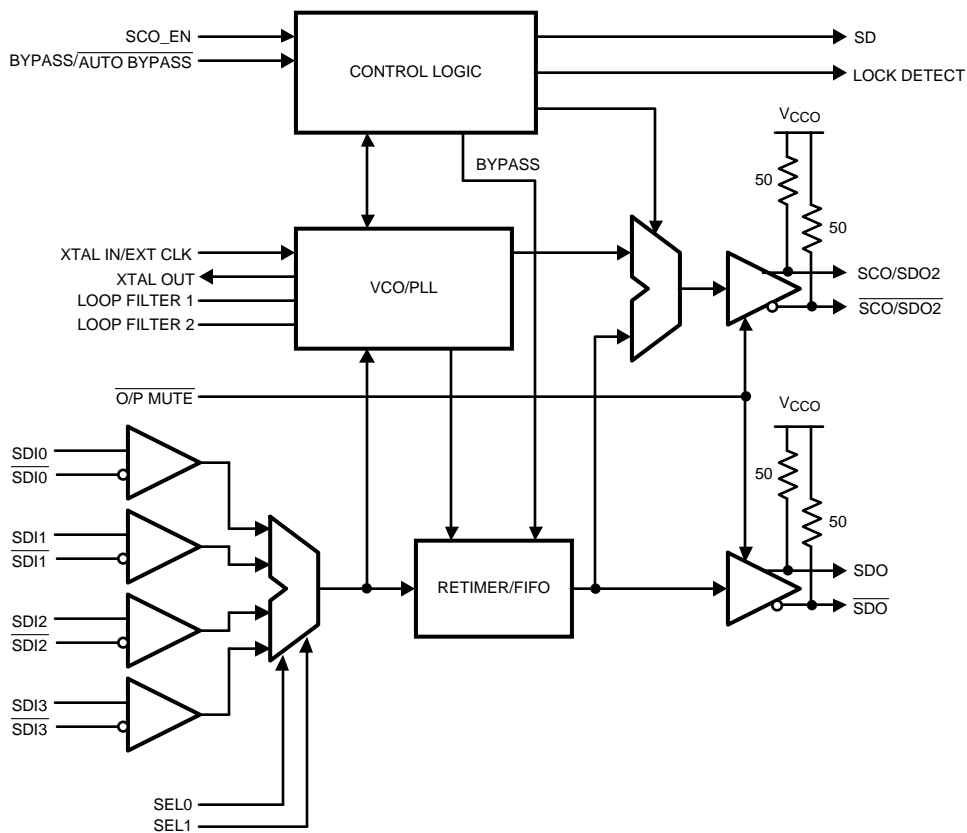
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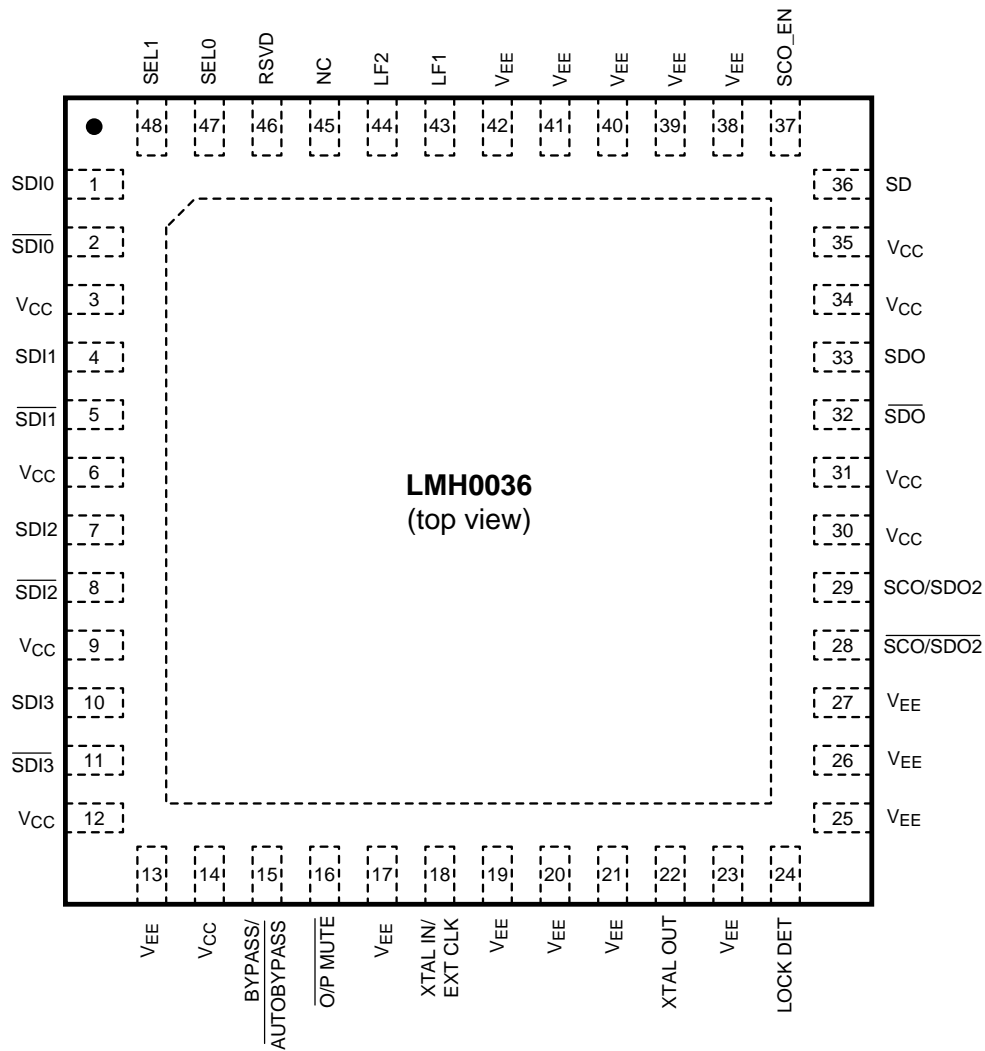
Typical Application



Block Diagram



Connection Diagram



The exposed die attach pad is the primary negative electrical terminal for this device. It must be connected to the negative power supply voltage.

**Figure 1. 48-Pin WQFN  
See Package Number RHS0048A**

### PIN DESCRIPTIONS

Pin	Name	Description
1	SDI0	Data Input 0 True.
2	$\overline{\text{SDI0}}$	Data Input 0 Complement.
4	SDI1	Data Input 1 True.
5	$\overline{\text{SDI1}}$	Data Input 1 Complement
7	SDI2	Data Input 2 True.
8	$\overline{\text{SDI2}}$	Data Input 2 Complement.
10	SDI3	Data Input 3 True.
11	$\overline{\text{SDI3}}$	Data Input 3 Complement.
15	BYPASS/ $\overline{\text{AUTO BYPASS}}$	Bypass/Auto Bypass mode select. Bypasses reclocking when high. This pin has an internal pulldown.
16	OUTPUT $\overline{\text{MUTE}}$	Data and Clock Output Mute input. Mutes the output when low. This pin has an internal pullup.
18	XTAL IN/EXT CLK	Crystal or External Oscillator input.
22	XTAL OUT	Crystal Oscillator output.
24	LOCK DETECT	PLL Lock Detect output (active high).
28	$\overline{\text{SCO/SDO2}}$	Serial Clock or Serial Data Output 2 complement.
29	SCO/SDO2	Serial Clock or Serial Data Output 2 true.
32	$\overline{\text{SDO}}$	Data Output complement.
33	SDO	Data Output true.
36	SD	SD indicator output. Output is high when locked to 270 Mbps.
37	SCO_EN	Serial Clock or Serial Data 2 Output select. Sets second output to output the clock when high and the data when low. This pin has an internal pulldown.
43	LF1	Loop Filter.
44	LF2	Loop Filter.
45	NC	No Connect. Not bonded internally.
46	RSVD	Reserved. Do not connect or connect to ground.
47	SEL0	Data Input select input. This pin has an internal pulldown.
48	SEL1	Data Input select input. This pin has an internal pulldown.
3, 6, 12, 14, 30, 31, 34, 35	V <sub>CC</sub>	Positive power supply input.
DAP, 13, 17, 19, 20, 21, 23, 25, 26, 27, 38, 39, 40, 41, 42	V <sub>EE</sub>	Negative power supply input.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

**ABSOLUTE MAXIMUM RATINGS<sup>(1)(2)</sup>**

Supply Voltage ( $V_{CC}-V_{EE}$ )		4.0V
Logic Supply Voltage ( $V_i$ )		$V_{EE}-0.15V$ to $V_{CC}+0.15V$
Logic Input Current (single input)	$V_i = V_{EE}-0.15V$	-5 mA
	$V_i = V_{CC}+0.15V$	+5 mA
Logic Output Voltage ( $V_o$ )		$V_{EE}-0.15V$ to $V_{CC}+0.15V$
Logic Output Source/Sink Current		±8 mA
Serial Data Input Voltage ( $V_{SDI}$ )		$V_{CC}$ to $V_{CC}-2.0V$
Serial Data Output Sink Current ( $I_{SDO}$ )		24 mA
Package Thermal Resistance	$\theta_{JA}$ 48-pin WQFN	26.1°C/W
	$\theta_{JC}$ 48-pin WQFN	1.9°C/W
Storage Temp. Range		-65°C to +150°C
Junction Temperature		+150°C
Lead Temperature (Soldering 4 Sec)		+260°C (Pb-free)
ESD Rating (HBM)		8 kV
ESD Rating (MM)		400V
ESD Rating (CDM)		1250V

- (1) "Absolute Maximum Ratings" are those parameter values beyond which the life and operation of the device cannot be ensured. The stating herein of these maximums shall not be construed to imply that the device can or should be operated at or beyond these values. [DC ELECTRICAL CHARACTERISTICS](#) and [AC ELECTRICAL CHARACTERISTICS](#) specify acceptable device operating conditions.
- (2) **It is anticipated that this device will not be offered in a military qualified version.** If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.

**RECOMMENDED OPERATING CONDITIONS**

Supply Voltage ( $V_{CC}-V_{EE}$ )	3.3V ±5%
Logic Input Voltage	$V_{EE}$ to $V_{CC}$
Differential Serial Input Voltage	800 mV ±10%
Serial Data or Clock Output Sink Current ( $I_{SO}$ )	16 mA max.
Operating Free Air Temperature ( $T_A$ )	-40°C to +85°C

**DC ELECTRICAL CHARACTERISTICS**

 Over Supply Voltage and Operating Temperature ranges, unless otherwise specified.<sup>(1)(2)</sup>

Symbol	Parameter	Conditions	Reference	Min	Typ	Max	Units
$V_{IH}$	Input Voltage High Level		Logic level inputs	2		$V_{CC}$	V
$V_{IL}$	Input Voltage Low Level			$V_{EE}$		0.8	V
$I_{IH}$	Input Current High Level	$V_{IH} = V_{CC}$		47		65	µA
$I_{IL}$	Input Current Low Level	$V_{IL} = V_{EE}$		-18		-25	µA
$V_{OH}$	Output Voltage High Level	$I_{OH} = -2$ mA	All logic level outputs	2			V
$V_{OL}$	Output Voltage Low Level	$I_{OL} = +2$ mA				$V_{EE} + 0.6$	V
$V_{SDID}$	Serial Input Voltage, Differential		SDI	200		1600	mV <sub>P-P</sub>
$V_{CMI}$	Input Common Mode Voltage	$V_{SDID} = 200$ mV	SDI	$V_{EE}+1.2$		$V_{CC}-0.2$	V
$V_{SDOD}$	Serial Output Voltage, Differential	100Ω differential load	SDO, SCO	720	800	880	mV <sub>P-P</sub>
$V_{CMO}$	Output Common Mode Voltage	100Ω differential load	SDO, SCO		$V_{CC} - V_{SDOD}$		V
$I_{CC}$	Power Supply Current, 3.3V supply, Total	270 Mbps, NTSC color bar pattern			109		mA

- (1) Current flow into device pins is defined as positive. Current flow out of device pins is defined as negative. All voltages are referenced to  $V_{EE}$  (equal to zero volts).
- (2) Typical values are stated for:  $V_{CC} = +3.3V$ ,  $T_A = +25^\circ C$ .

## AC ELECTRICAL CHARACTERISTICS

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified.<sup>(1)</sup>

Symbol	Parameter	Conditions	Reference	Min	Typ	Max	Units
BR <sub>SD</sub>	Serial Data Rate	SMPTE 259M (C)	SDI, SDO		270		Mbps
TOL <sub>JIT</sub>	Serial Input Jitter Tolerance	270 Mbps <sup>(2)(3)(4)</sup>	SDI	>6			UI <sub>P-P</sub>
TOL <sub>JIT</sub>	Serial Input Jitter Tolerance	270 Mbps <sup>(2)(3)(5)</sup>	SDI	>0.6			UI <sub>P-P</sub>
t <sub>JIT</sub>	Serial Data Output Jitter	270 Mbps <sup>(3)(6)</sup>	SDO		0.02	0.08	UI <sub>P-P</sub>
BW <sub>LOOP</sub>	Loop Bandwidth	270 Mbps, <0.1dB Peaking			300		kHz
F <sub>CO</sub>	Serial Clock Output Frequency	270 Mbps data rate	SCO		270		MHz
t <sub>JIT</sub>	Serial Clock Output Jitter				2	3	ps <sub>RMS</sub>
	Serial Clock Output Alignment with respect to Data Interval		SDO, SCO	40		60	%
	Serial Clock Output Duty Cycle		SCO	45		55	%
T <sub>ACQ</sub>	Acquisition Time	See <sup>(7)(8)</sup>				15	ms
t <sub>r</sub> , t <sub>f</sub>	Input rise/fall time	10%–90%	Logic inputs		1.5	3	ns
t <sub>r</sub> , t <sub>f</sub>	Input rise/fall time	20%–80%	SDI			1500	ps
t <sub>r</sub> , t <sub>f</sub>	Output rise/fall time	10%–90%	Logic outputs		1.5	3	ns
t <sub>r</sub> , t <sub>f</sub>	Output rise/fall time	20%–80% <sup>(9)</sup>	SCO, SDO		90	130	ps
F <sub>REF</sub>	Reference Clock Frequency				27		MHz
F <sub>TOL</sub>	Ref. Clock Freq. Tolerance				±50		ppm

(1) Typical values are stated for: V<sub>CC</sub> = +3.3V, T<sub>A</sub> = +25°C.

(2) Peak-to-peak amplitude with sinusoidal modulation per SMPTE RP 184-1996 paragraph 4.1. The test data signal shall be color bars.

(3) This parameter is ensured by characterization over voltage and temperature limits.

(4) Refer to "A1" in Figure 1 of SMPTE RP 184-1996.

(5) Refer to "A2" in Figure 1 of SMPTE RP 184-1996.

(6) Serial Data Output Jitter is total output jitter with 0.2UI<sub>P-P</sub> input jitter.

(7) Specification is ensured by design.

(8) Measured from first SDI transition until Lock Detect (LD) output goes high (true).

(9) R<sub>L</sub> = 100Ω differential.

## DEVICE DESCRIPTION

The LMH0036 SD SDI Reclocker with 4:1 Input Multiplexer is used in many types of digital video signal processing equipment. The LMH0036 supports the SMPTE 259M (C) standard, with a corresponding serial data rate of 270 Mbps. DVB-ASI data at 270 Mbps may also be retimed. The LMH0036 retimes the serial data stream to suppress accumulated jitter. It provides two low-jitter, differential, serial data outputs. The second output may be selected to output either serial data or a low-jitter serial data-rate clock. Controls and indicators are: serial data-rate clock or second serial data output select, manual rate select input, SD indicator output, lock detect output, auto/manual data bypass and output mute.

Serial data inputs are CML and LVPECL compatible. Serial data and data-rate clock outputs are differential CML and produce LVPECL compatible levels. The output buffer design can drive AC or DC-coupled, terminated 100Ω differential loads. The differential output level is 800 mV<sub>P-P</sub> ±10% into 100Ω AC or DC-coupled differential loads. Logic inputs and outputs are LVCMOS compatible.

The device package is a 48-pin WQFN with an exposed die attach pad. The exposed die attach pad is electrically connected to device ground (V<sub>EE</sub>) and is the primary negative electrical terminal for the device. This terminal must be connected to the negative power supply or circuit ground.

### Serial Data Inputs, Serial Data and Clock Outputs

#### SERIAL DATA INPUT AND OUTPUTS

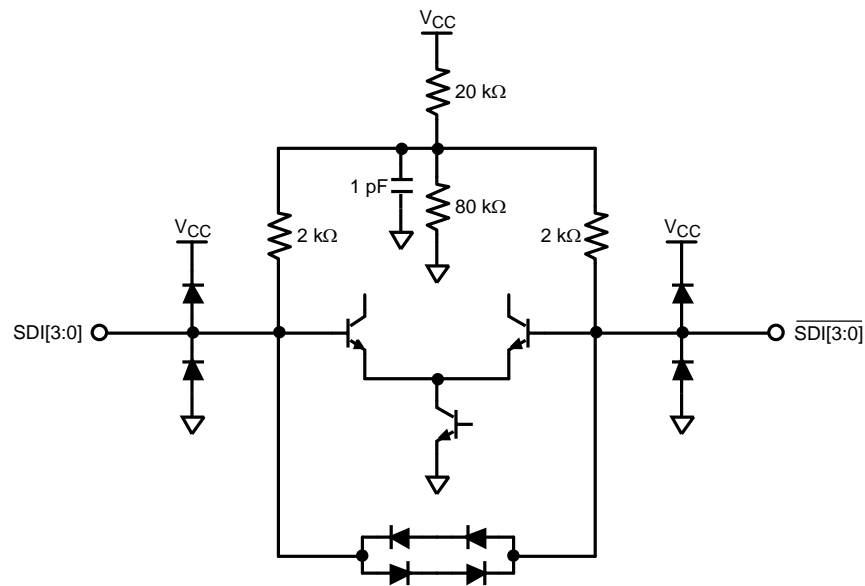
The differential serial data inputs, SDI0-SDI3, accept 270 Mbps serial digital video data. The serial data inputs are differential LVPECL compatible. These inputs are intended to be DC interfaced to devices such as the LMH0074 adaptive cable equalizer. These inputs are not internally terminated or biased. The inputs may be AC-coupled if a suitable input bias voltage is provided.

The LMH0036 provides four independent, multiplexed data inputs. The active input channel is selected via the SEL0 and SEL1 pins, as shown in [Table 1](#). [Figure 2](#) shows the equivalent input circuit for SDI[3:0] and  $\overline{\text{SDI}}[3:0]$ .

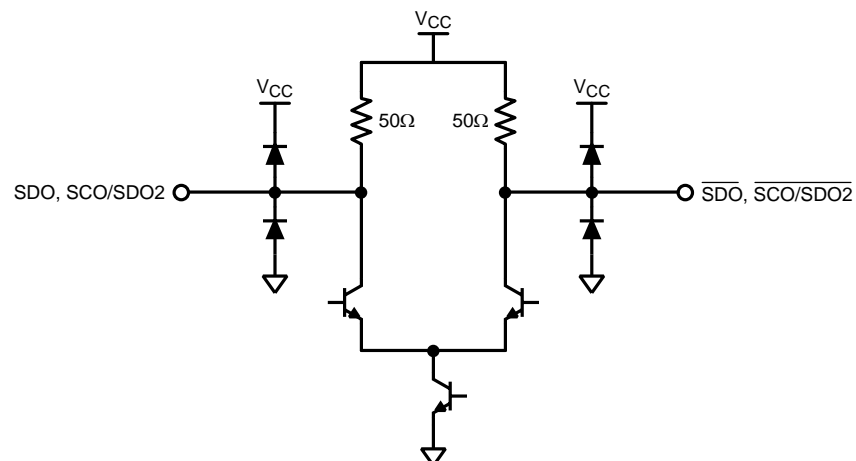
The LMH0036 has two, retimed, differential, serial data outputs, SDO and SCO/SDO2. These outputs provide low jitter, differential, retimed data to devices such as the LMH0001 or LMH0002 cable driver. Output SCO/SDO2 is multiplexed and can provide either a second serial data output or a serial data-rate clock output. [Figure 3](#) shows the equivalent output circuit for SDO,  $\overline{\text{SDO}}$ , SCO/SDO2, and  $\overline{\text{SCO/SDO2}}$ .

The SCO\_EN input controls the operating mode for the SCO/SDO2 output. When the SCO\_EN input is high the SCO/SDO2 output provides a serial data-rate clock. When SCO\_EN is low, the SCO/SDO2 output provides retimed serial data.

Both differential serial data outputs, SDO and SCO/SDO2, are muted when the OUTPUT  $\overline{\text{MUTE}}$  input is a logic low level. SCO/SDO2 also mutes when the Bypass mode is activated when this output is operating as the serial clock output. When muted, SDO and  $\overline{\text{SDO}}$  (or SDO2 and  $\overline{\text{SDO2}}$ ) will assume opposite differential output levels. The CML serial data outputs are differential LVPECL compatible. These outputs have internal 50Ω pull-ups and are suitable for driving AC or DC-coupled, 100Ω center-tapped, AC grounded or 100Ω un-center-tapped, differentially terminated networks.



**Figure 2. Equivalent SDI Input Circuit (SDI[3:0],  $\overline{\text{SDI[3:0]}}$ )**



**Figure 3. Equivalent SDO Output Circuit (SDO,  $\overline{\text{SDO}}$ , SCO/SDO2,  $\overline{\text{SCO/SDO2}}$ )**

### SERIAL DATA CLOCK/SERIAL DATA 2 OUTPUT

The Serial Data Clock/Serial Data 2 Output is controlled by the SCO\_EN input and provides either a second retimed serial data output or a low jitter differential clock output appropriate to the serial data rate being processed. When operating as a serial clock output, the rising edge of the clock will be positioned within the corresponding serial data bit interval within 10% of the center of the data interval.

Differential output SCO/SDO2 functions as the second serial data output when the SCO\_EN input is a logic-low level. This output functions as the serial data-rate clock output when the SCO\_EN input is a logic-high level. The SCO\_EN input has an internal pull-down device and the default state of SCO\_EN is low (serial data output 2 enabled). SCO/SDO2 is muted when the OUTPUT MUTE input is a logic low level. When the Bypass mode is activated and this output is functioning as a serial clock output, the output will also be muted. If an unsupported data rate is used while in Auto Bypass mode with this output functioning as a serial clock output, the output is invalid.

## Control Inputs and Indicator Outputs

### SERIAL DATA INPUT SELECTOR

The Serial Data Input Selector (SEL [1:0]) allows the user to select the active input channel. [Table 1](#) shows the input selected for a given state of SEL [1:0].

**Table 1. Data Input Select Codes**

SEL [1:0] Code	Selected Input
00	SDI0
01	SDI1
10	SDI2
11	SDI3

### LOCK DETECT

The Lock Detect (LD) output, when high, indicates that data is being received and the PLL is locked. LD may be connected to the OUTPUT MUTE input to mute the data and clock outputs when no data signal is being received. Note that when the Bypass/Auto Bypass input is set high, Lock Detect will remain low. See [Table 2](#).

### OUTPUT MUTE

The OUTPUT MUTE input, when low, mutes the serial data and clock outputs. It may be connected to Lock Detect or externally driven to mute or un-mute the outputs. If OUTPUT MUTE is connected to LD, then the data and clock outputs are muted when the PLL is not locked. This function overrides the Bypass function: see [Table 2](#). OUTPUT MUTE has an internal pull-up device to enable the output by default.

### BYPASS/AUTO BYPASS

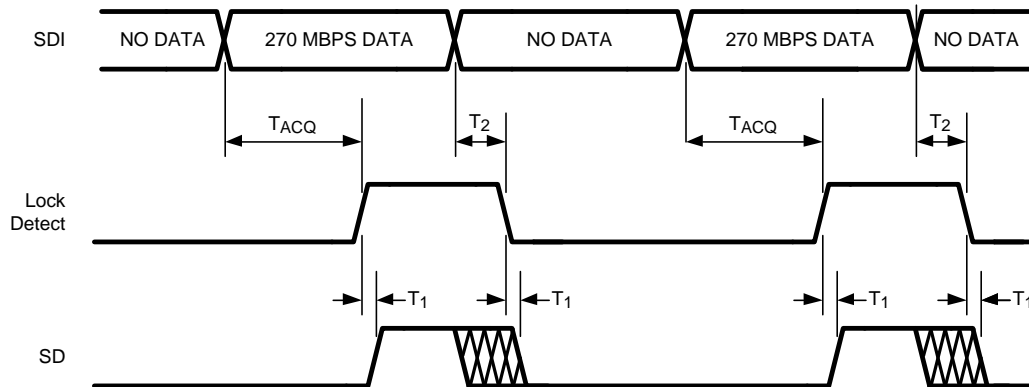
The Bypass/Auto Bypass input, when high, forces the device to output the data without reclocking it. When this input is low, the device automatically bypasses the reclocking function when the device is in an unlocked condition or the detected data rate is a rate which the device does not support. Note that when the Bypass/Auto Bypass input is set high, Lock Detect will remain low. See [Table 2](#). BYPASS/AUTO BYPASS has an internal pull-down device.

**Table 2. Control Functionality**

LOCK DETECT	OUTPUT MUTE	BYPASS/AUTO BYPASS	DEVICE STATUS
0	1	X	PLL unlocked, reclocker bypassed
1	1	0	PLL locked to supported data rate, reclocker not bypassed
X	0	X	Outputs muted
0	LOCK DETECT	X	Outputs muted
1	LOCK DETECT	0	PLL locked to supported data rate, reclocker not bypassed

### SD

The SD output indicates that the LMH0036 is locked and processing SD data rates. It may be used to control another device such as the LMH0002 cable driver. When this output is high it indicates that the data rate is 270 Mbps. The SD output is a registered function and is only valid when the PLL is locked and the Lock Detect output is high. The SD output is undefined for a short time after lock detect assertion or de-assertion due to a data change on the SDI input. See [Figure 4](#) for a timing diagram showing the relationship between SDI, Lock Detect, and SD.



$T_{ACQ}$  = Acquisition Time, defined in the AC Electrical Characteristics Table

$T_1$  = Time from Lock Detect assertion or deassertion until SD output is valid, typically 37ns (one 27 MHz clock period)

$T_2$  = Time from SDI input change until Lock Detect de-assertion, 1 ms maximum. SD output is not valid during this time.

**Figure 4. SDI, Lock Detect, and SD Timing**

## SCO\_EN

Input SCO\_EN enables the SCO/SDO2 differential output to function either as a serial data-rate clock or second serial data output. SCO/SDO2 functions as a serial data-rate clock when SCO\_EN is high. This pin has an internal pull-down device. The default state (low) enables the SCO/SDO2 output as a second serial data output.

## CRYSTAL OR EXTERNAL CLOCK REFERENCE

The LMH0036 uses a 27 MHz crystal or external clock signal as a timing reference input. A 27 MHz parallel resonant crystal and load network may be connected to the XTAL IN/EXT CLK and XTAL OUT pins. Alternatively, a 27 MHz LVCMOS compatible clock signal may be input to XTAL IN/EXT CLK. Parameters for a suitable crystal are given in [Table 3](#).

**Table 3. Crystal Parameters**

Parameter	Value
Frequency	27 MHz
Frequency Stability	±100 ppm @ recommended drive level
Operating Mode	Fundamental mode, Parallel Resonant
Load Capacitance	20 pF
Shunt Capacitance	7 pF
Series Resistance	40Ω max.
Recommended Drive Level	100 μW
Maximum Drive Level	500 μW
Operating Temperature Range	-10°C to +60°C

APPLICATION INFORMATION

Figure 5 shows a application circuit for the LMH0036.

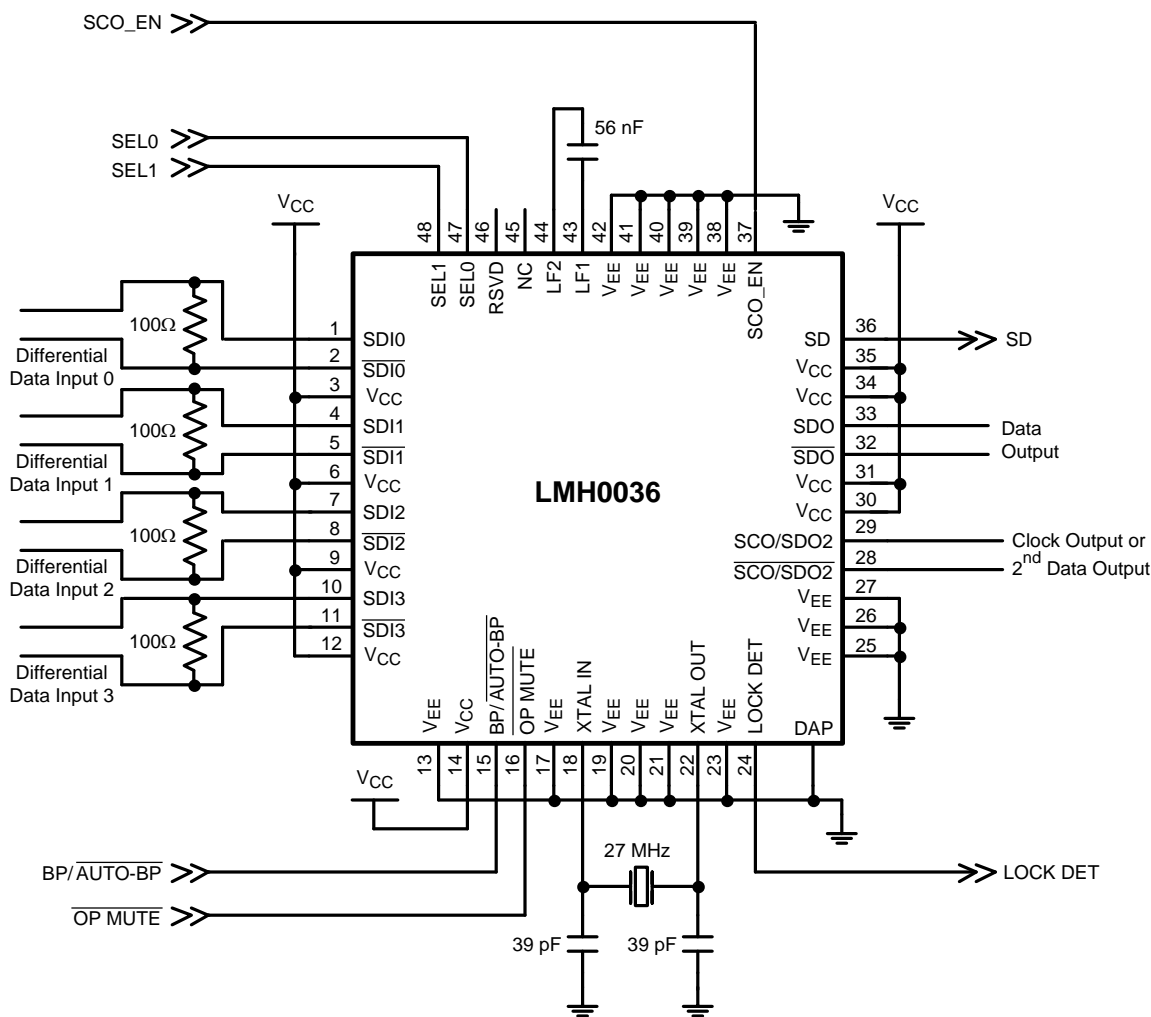


Figure 5. Application Circuit

BYPASS/AUTO BYPASS has an internal pulldown to enable Auto Bypass mode by default. This pin may be pulled high to force the LMH0036 to bypass all data.

OUTPUT MUTE has an internal pullup to enable the outputs by default. This pin may be pulled low to mute the outputs.

The XTAL IN/EXT CLK and XTAL OUT pins are shown with a 27 MHz crystal and the proper loading. The crystal should match the parameters described in Table 3. Alternately, a 27MHz LVCMOS compatible clock signal may be input to XTAL IN/EXT CLK.

The active high LOCK DETECT output provides an indication that proper data is being received and the PLL is locked.

The SD output may be used to drive the SD/H $\bar{D}$  pin of an SDI cable driver (such as the LMH0002) in order to properly set the cable driver's edge rate for SMPTE compliance. It defaults to low when the LMH0036 is not locked.

SCO\_EN has an internal pulldown to set the second output (SCO/SDO2) to output data. This pin may be pulled high to set the second output as a serial clock.

The external loop filter capacitor (between LF1 and LF2) should be 56 nF. This is the only supported value; the loop filter capacitor should not be changed.

SEL0 and SEL1 have internal pulldowns to select the SDI0 input by default.

The inputs are LVPECL compatible. The LMH0036 has a wide input common mode range and in most cases the input should be DC coupled. For DC coupling, the inputs must be kept within the common mode range specified in [DC ELECTRICAL CHARACTERISTICS](#).

Figure 6 shows an example of a DC coupled interface between the LMH0074 cable equalizer and the LMH0036. The LMH0074 output common mode voltage and voltage swing are within the range of the input common mode voltage and voltage swing of the LMH0036. All that is required is a 100Ω differential termination as shown. The resistor should be placed as close as possible to the LMH0036 input. If desired, this network may be terminated with two 50Ω resistors and a center tap capacitor to ground in place of the single 100Ω resistor.

The outputs are LVPECL compatible. SDO is the primary data output and SCO/SDO2 is a second output that may be set as the serial clock or a second data output. Both outputs are always active. The LMH0036 output should be DC coupled to the input of the receiving device as long as the common mode ranges of both devices are compatible.

Figure 7 shows an example of a DC coupled interface between the LMH0036 and LMH0001 cable driver. All that is required is a 100Ω differential termination as shown. The resistor should be placed as close to the LMH0302 input as possible. If desired, this network may be terminated with two 50Ω resistors and a center tap capacitor to ground in place of the single 100Ω resistor.

The LMH0036 has multiple ground connections, however; the primary ground connection is through the large exposed DAP. The DAP must be connected to ground for proper operation of the LMH0036.

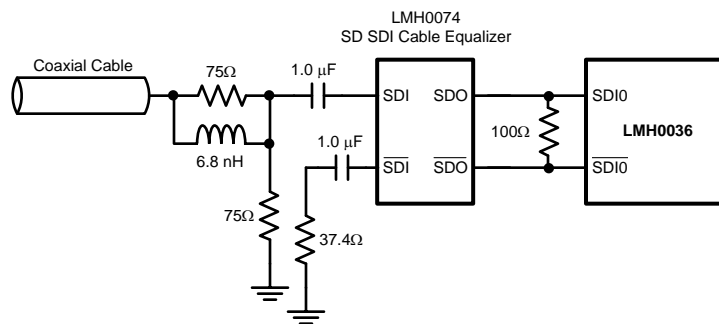


Figure 6. DC Input Interface

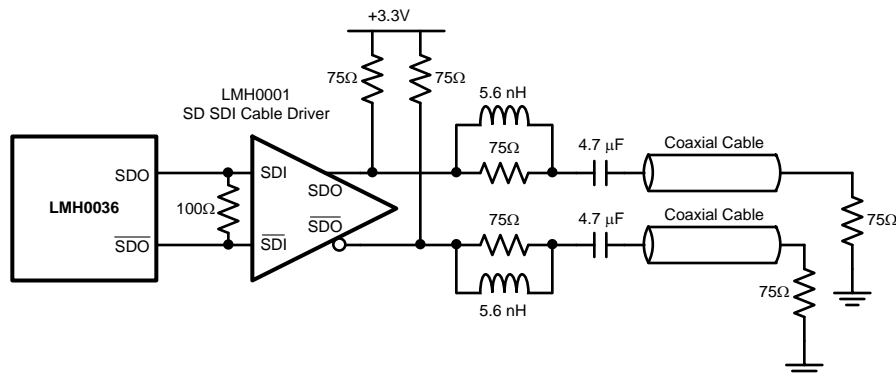


Figure 7. DC Output Interface

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**REVISION HISTORY**

<b>Changes from Revision A (April 2013) to Revision B</b>	<b>Page</b>
• Changed layout of National Data Sheet to TI format .....	<a href="#">12</a>

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**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LMH0036SQE/NOPB	ACTIVE	WQFN	RHS	48	250	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 85	XL036	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

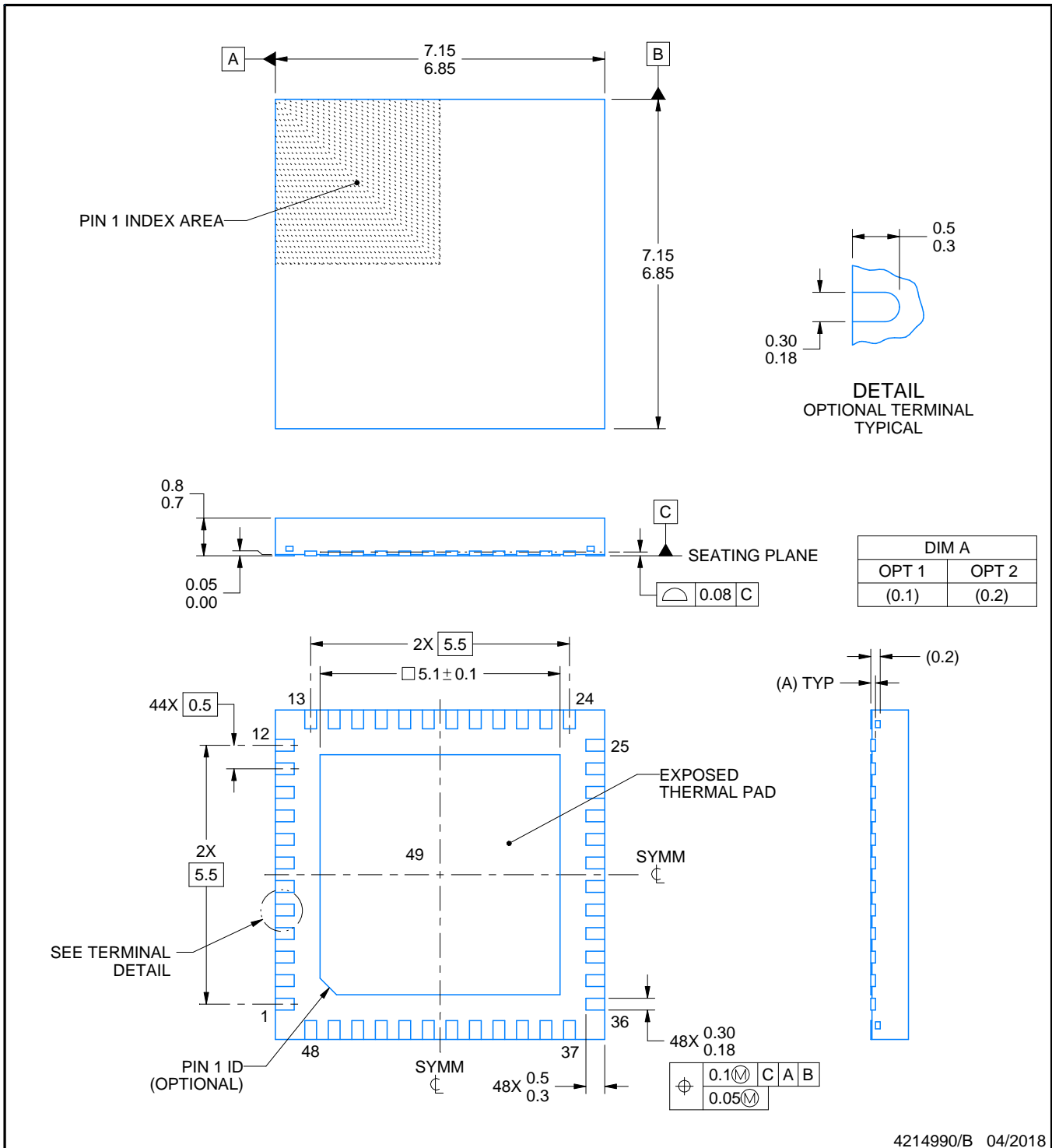
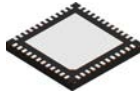
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMH0036SQE/NOPB	WQFN	RHS	48	250	178.0	16.4	7.3	7.3	1.3	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMH0036SQE/NOPB	WQFN	RHS	48	250	210.0	185.0	35.0



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NOTES:

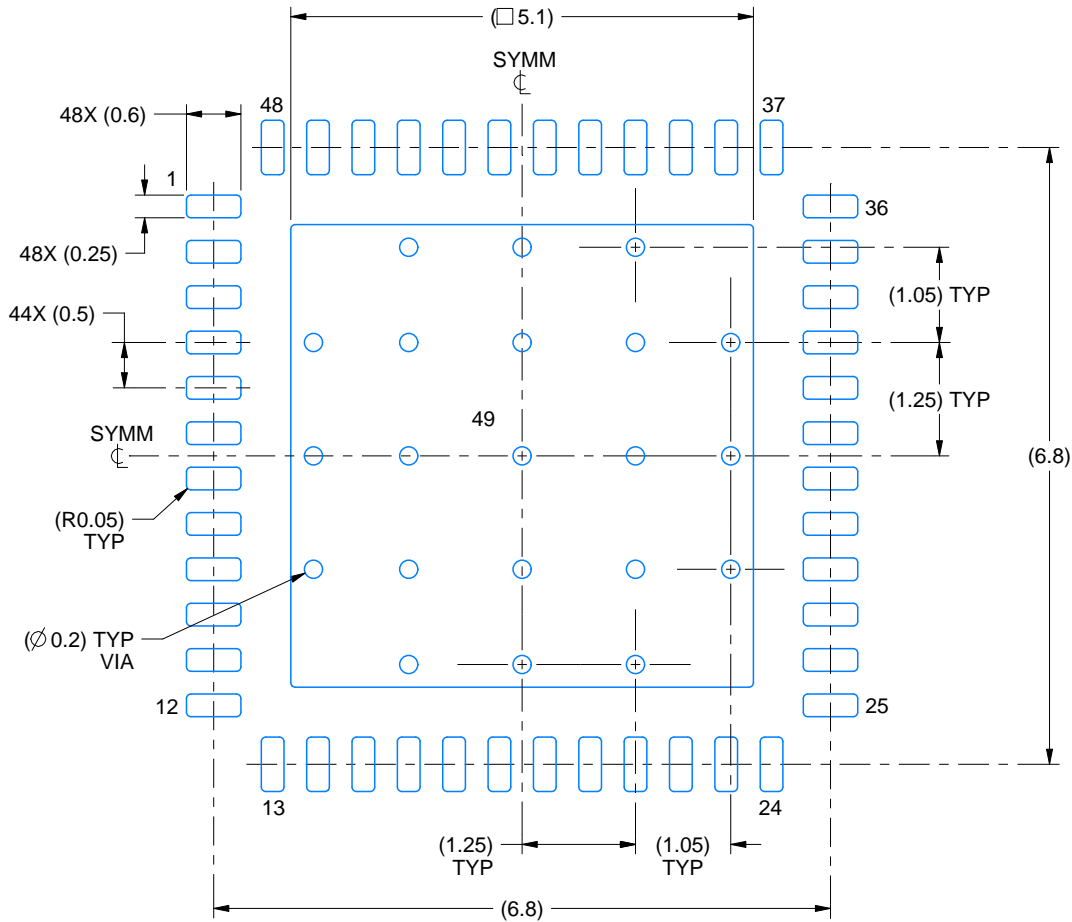
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

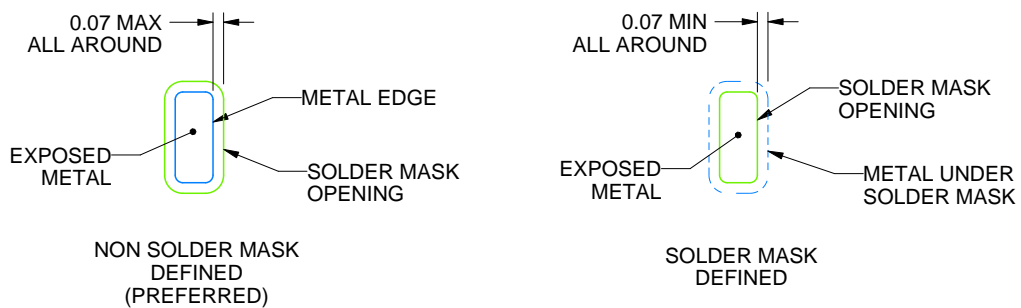
RHS0048A

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



**LAND PATTERN EXAMPLE**  
EXPOSED METAL SHOWN  
SCALE:12X



**SOLDER MASK DETAILS**

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NOTES: (continued)

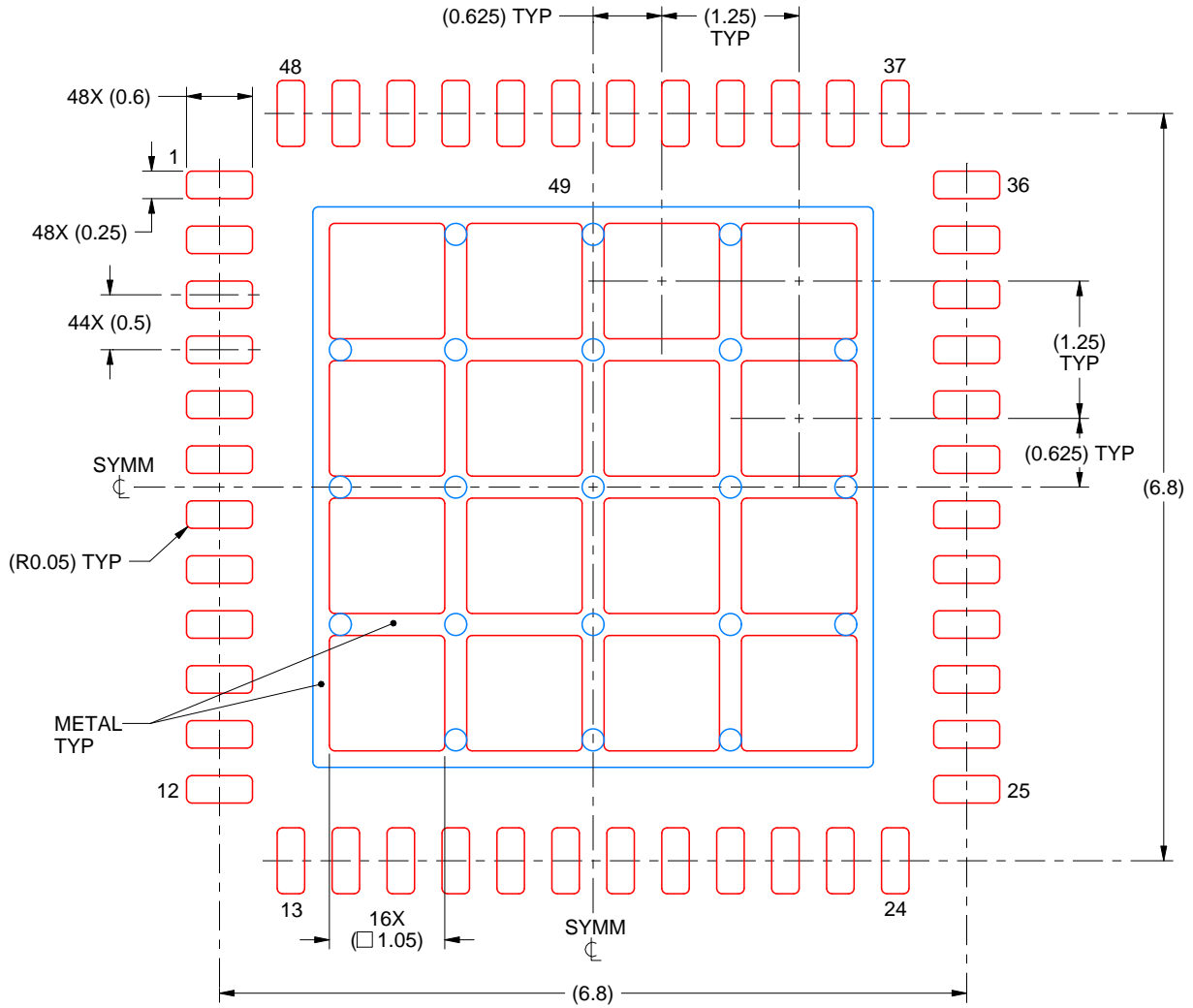
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

RHS0048A

WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



**SOLDER PASTE EXAMPLE**  
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 49  
68% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
SCALE:15X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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